

IN THE CLAIMS:

Please **CANCEL** claims 12 and 17 without prejudice or disclaimer.

Please **REWRITE** claim 11 as follows:

11. (Twice Amended) A method for packaging integrated circuits, comprising:
providing a lead frame of a conductive material with an array of lead posts that are
equally spaced apart and a connecting sheet connecting each of the lead posts;
attaching a plurality of first dice to the lead frame, wherein each first die is electrically and
mechanically connected to a plurality of lead posts within the array of lead posts, and wherein a
conductive side of each first die faces the lead posts; **[and]**
encapsulating the plurality of dice with an encapsulating material; **and**
removing a thin portion of the connecting sheet between each of the lead posts to
electrically isolate each of the lead posts wherein an unremoved portion of the connecting
sheet remains connected to each lead post and forms an oversized contact pad on a bottom
surface of the packaged integrated circuits, wherein the oversized contact pad has a
diameter that is larger than a diameter of each of the lead posts.

Please **ADD** the following new claims 23-29:

23. (New) A method as recited in claim 11 wherein the removing of the thin portions of the
connecting sheet is performed by passing a rotating saw blade over the connecting sheet.
24. (New) A method as recited in claim 11 wherein the connecting sheet is imperforate and
wherein the array of lead posts are integrally formed with the connecting sheet and extend from a
top surface of the connecting sheet.
25. (New) A method for manufacturing a packaged semiconductor device comprising:
providing a conductive lead frame having an imperforate connecting sheet and an array
of integrally formed lead posts that extend from a top surface of the connecting sheet;
attaching a plurality of semiconductor dice onto the lead frame wherein a first surface of
each die, which has contact pads, is placed in contact with the array of lead posts;

applying liquid molding material over the dice and lead frame such that the molding material fills in voids between the lead posts and covers the dice.

26. (New) A method as recited in claim 25 further comprising:

removing a thin portion of the connecting sheet between each of the lead posts to electrically isolate each of the lead posts wherein an unremoved portion of the connecting sheet remains connected to each lead post and forms an oversized contact pad on a bottom surface of the packaged semiconductor device, wherein the oversized contact pad has a diameter that is larger than a diameter of each of the lead posts.

27. (New) A method as recited in claim 26 further comprising:

singulating each of the packaged semiconductor devices from the lead frame.

28. (New) A method as recited in claim 25 further comprising:

curing the liquid molding material so that a single flat molding material panel encapsulates multiple semiconductor dice.

29. (New) A method as recited in claim 11 wherein the encapsulating material is formed into a single flat panel that encapsulates the plurality of dice.